

SPECIFICATION FOR TFT MODULE

MODULE NO: YB-TG240240S02A-N-A1

Doc.Version:02

Customer Approval:

<input type="checkbox"/> Accept	<input type="checkbox"/> Reject
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YEEBO	NAME	SIGNATURE	DATE
Prepare	Electronic Engineer	李李志	2022-11-11
Check	Mechanical Engineer	周健文	2022-11-14
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■ APPROVAL FOR SPECIFICATIONS ONLY

□ APPROVAL FOR SPECIFICATIONS AND SAMPLE



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WIMRD005-02-D

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1. Revision History

Sample Version	DOC. Version	DATE	DESCRIPTION		CHANGED BY
A0	00	2021-06-22	Spec Only	First issue	F.J.W/Z.J.W
A0	01	2021-08-17	Full Spec	First Sample	F.J.W/Z.J.W
A1	02	2022-11-11	Spec Only	Second issue	L.M.Z/Z.J.W

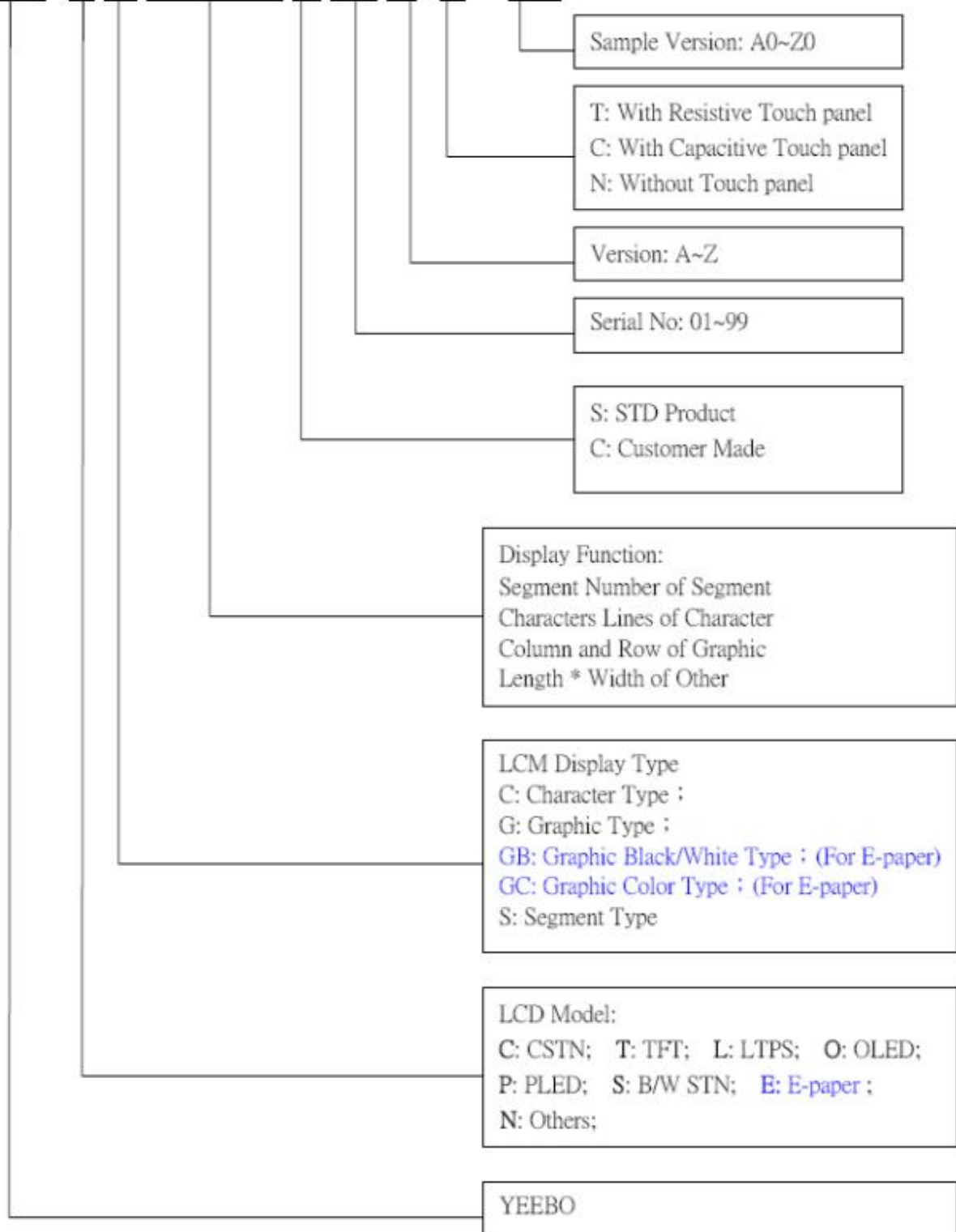
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3. Module Numbering System:

(Example)

YB- T G 240320 S 01 D -T - A0



4. General Specification:

ITEM	CONTENTS
Module Size	49.0 (W) * 56.5 (H) * 2.16 (T) mm
Module Size(With FPC)	55.6 (W) * 57.5 (H) * 2.16 (T) mm
Display Size(Diagonal)	2.4 inch
Display Format	240(RGB)* 240 Pixels
Active Area	43.2(W) * 43.2 (H) mm
Pixel Pitch	0.18* 0.18 mm
LCD Type	TFT (262K)/ Transmissive / NB
View Direction:	Free
Controller IC	ST7789V-G4
Weight	TBD

5. LCM drawing:

Count drawing & Spec. revision record during discussion with customer		
Rev.	Revision content description	Date
#1	FIRST ISSUE	2021-06-23
#2	Modify BLG&LCD	2022-11-14

Specifications:

1. Display mode: 2.4" TFT/ Transmissive
2. Display Color: 262K
3. Viewing Direction: Full View
4. Driver IC: ST7789V
5. Operating temperature: -20°C to +70°C
6. Backlight: chip White LED
7. Unspecified tolerance: ±0.30mm.
8. ROHS compliant
9. Luminous Intensity for LCM: 500cd/m²(min), 600cd/m²(typ)
10. 产品结构: 全贴

Detail "B"
Scale: 5x

Detail "C"
Scale: 100x

Detail "A"
Scale: 4x

CIRCUIT DIAGRAM
B/L Electrical Circuit
(Vf=8.5V~10.2V, If=40mA)

Connector: FH26W-35S-0.3SHW
Scale: 4x

LCD MODULE	
NO.	SYMBOL
1	GND
2	IM0
3	IM1
4	TE
5	GND
6	DB17
7	DB16
8	DB15
9	DB14
10	DB13
11	DB12
12	DB11
13	DB10
14	DB9
15	DB8
16	IOVCC
17	DB7
18	DB6
19	DB5
20	DB4
21	DB3
22	DB2
23	DB1
24	DB0
25	/CS
26	RS
27	WR
28	RD
29	/REST
30	VCI
31	GND
32	LED+
33	GND
34	LED-
35	GND

YEEBO		UNIT	SIZE	SCALE	DESIGNED	CHECKED	VERIFIED	APPROVED	FILE NAME
		mm	A4	N-T-S	周健文				
		Sheet	1	Of	1				

6. Electrical Characteristics

6-1 Absolute Maximum Ratings

(Ta=25°C VSS=0V)

Item	Symbol	Min.	Type	Max.	Unit	Remark
Input Voltage	V _{DD}	-0.3	-	+4.6	Volt	Note1
Supply Voltage(Logic)	IOV _{CC}	-0.3	-	+4.6	V	Note1
Logic Input Voltage Range	V _{IN}	-0.3	-	IOV _{CC} +0.5	V	Note1
Operating Temperature	Topr	-20	-	+70	°C	-
Storage Temperature	Tstg	-30	-	+80	°C	-

Note1: Absolute maximum rating is the limit value beyond which the IC maybe broken.
They do not assure operations.

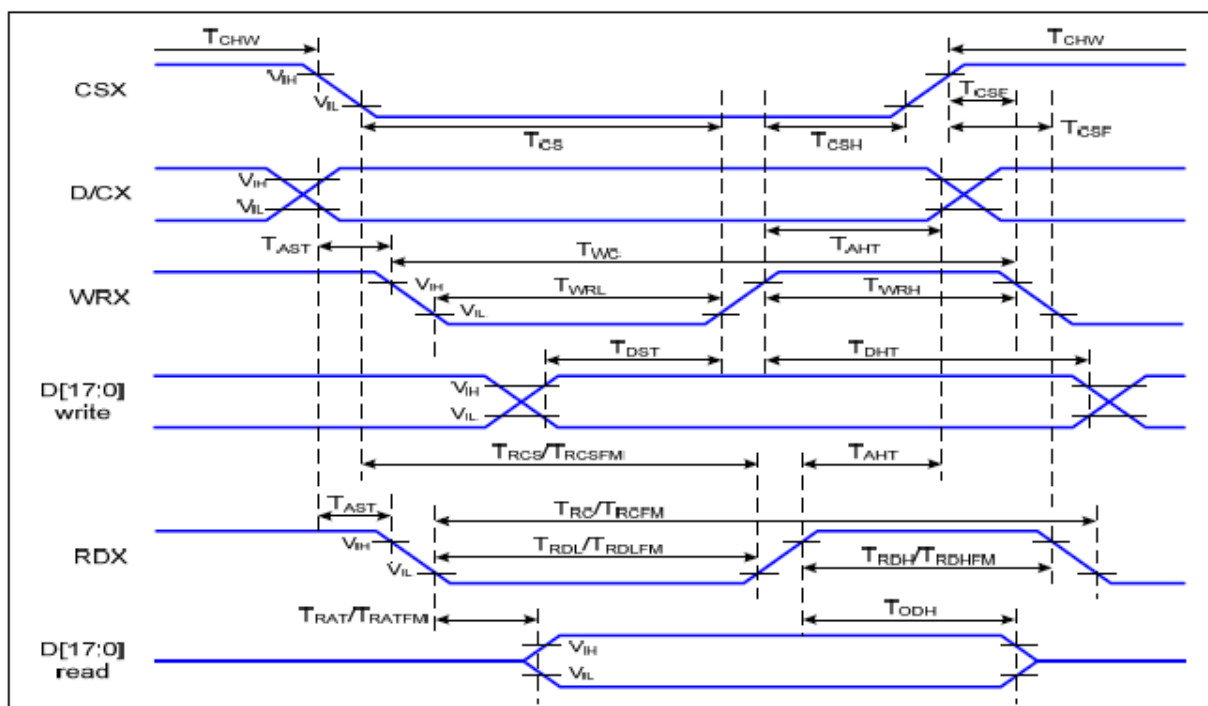
6-2 Operating Conditions

(Ta=25°C)

Item	Symbol	Condition	Min.	Typ.	Max.	Unit
Power Supply voltage	V _{CI}	-	2.6	2.8	3.3	v
Supply voltage for I/O	IOV _{CC}	-	1.65	1.8	3.3	v
Input Voltage	V _{IH}	-	0.7* IOV _{CC}	-	IOV _{CC}	v
	V _{IL}	-	GND	-	0.3* IOV _{CC}	v
Power Supply Current for LCM	I _{CC}	V _{CI} =2.8V	-	TBD	-	mA

6-3 Timing Characteristics

8080 Series MCU Parallel Interface Characteristics: 18/16/9/8-bit Bus



Parallel Interface Timing Characteristics (8080-Series MCU Interface)

VDD1=1.65 to 3.3V, VDD=2.4 to 3.3V, AGND=DGND=0V, Ta= -30 to 70 °C

Signal	Symbol	Parameter	Min	Max	Unit	Description
D/CX	T _{AST}	Address setup time	0		ns	
	T _{AHT}	Address hold time (Write/Read)	10		ns	
CSX	T _{CHW}	Chip select "H" pulse width	0		ns	
	T _{CS}	Chip select setup time (Write)	15		ns	
	T _{RCS}	Chip select setup time (Read ID)	45		ns	
	T _{RCSFM}	Chip select setup time (Read FM)	355		ns	
	T _{CSF}	Chip select wait time (Write/Read)	10		ns	
	T _{CSH}	Chip select hold time	10		ns	
WRX	T _{WC}	Write cycle	66		ns	
	T _{WRH}	Control pulse "H" duration	15		ns	
	T _{WRL}	Control pulse "L" duration	15		ns	
RDX (ID)	T _{RC}	Read cycle (ID)	160		ns	When read ID data
	T _{RDH}	Control pulse "H" duration (ID)	90		ns	
	T _{RDL}	Control pulse "L" duration (ID)	45		ns	
RDX (FM)	T _{RCFM}	Read cycle (FM)	450		ns	When read from frame memory
	T _{RDHFM}	Control pulse "H" duration (FM)	90		ns	
	T _{RDLFM}	Control pulse "L" duration (FM)	355		ns	
D[17:0]	T _{DST}	Data setup time	10		ns	For CL=30pF

	T _{DHT}	Data hold time	10		ns
	T _{RAT}	Read access time (ID)		40	ns
	T _{RATFM}	Read access time (FM)		340	ns
	T _{ODH}	Output disable time	20	80	ns

7. Optical Characteristics:

Item	Symbol	Conditions	Specifications			Unit	Note	
			Min	Typ	Max			
Transmittance (Without PLZ)	T (%)	-	-	3.9	-	-	-	
Contrast Ratio	CR	$\Theta=0$ Normal Viewing angle	600	800	-	-	(1) (2)	
Response time	TR+TF	-	-	30	-	ms	(1) (3)	
Viewing angle	Hor.	Θ_{x+}	CR ≥ 10	-	80	-	deg.	-
		Θ_{x-}		-	80	-		
	Ver.	Θ_{y+}		-	80	-		
		Θ_{y-}		-	80	-		

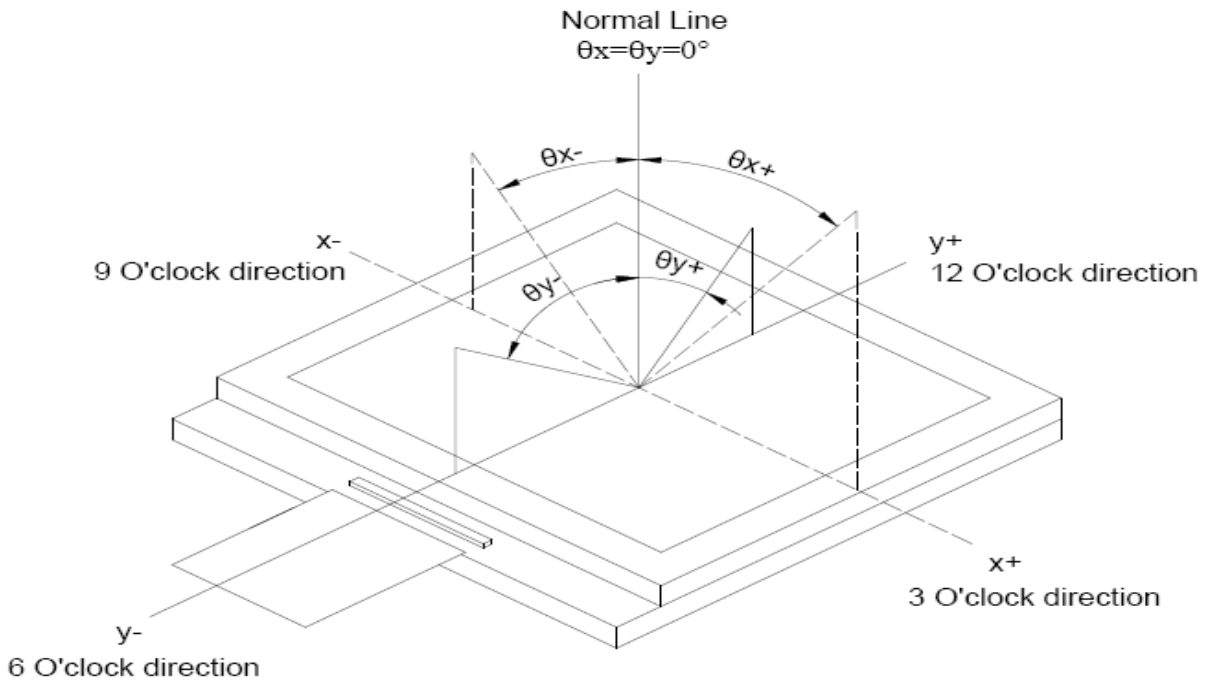
Measuring Condition

1. Measuring surrounding: dark room
2. Ambient temperature: 25±2°C
3. 30 min. Warm-up time.

Color of CIE Coordinate:

Item	Symbol	Condition	Min.	Typ.	Max.	
Chromaticity Coordinates (Transmissive)	Red	x	$\theta = \phi = 0^\circ$ LED Backlight	TBD	0.641	TBD
		y		TBD	0.337	TBD
	Green	x		TBD	0.274	TBD
		y		TBD	0.560	TBD
	Blue	x		TBD	0.141	TBD
		y		TBD	0.113	TBD
	White	x		TBD	0.308	TBD
		y		TBD	0.330	TBD

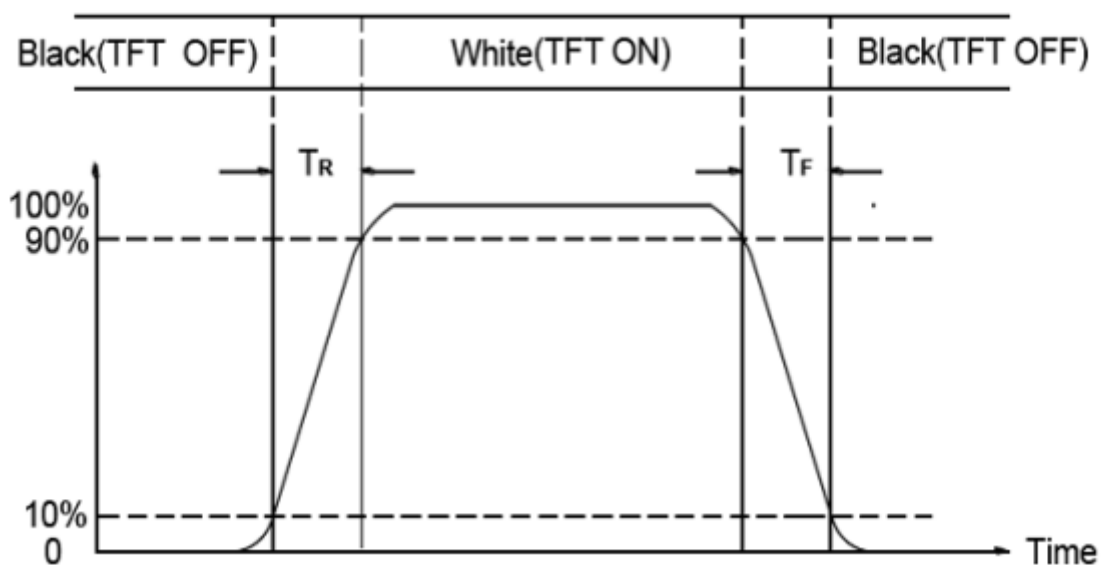
Note (1) Definition of Viewing Angle:



Note (2) Definition of Contrast Ratio (CR):
measured at the center point of panel

$$\text{Contrast ratio (CR)} = \frac{\text{Photo detector output when LCD is at "White" state}}{\text{Photo detector output when LCD is at "Black" state}}$$

Note (3) Definition of Response Time: Sum of TR and TF

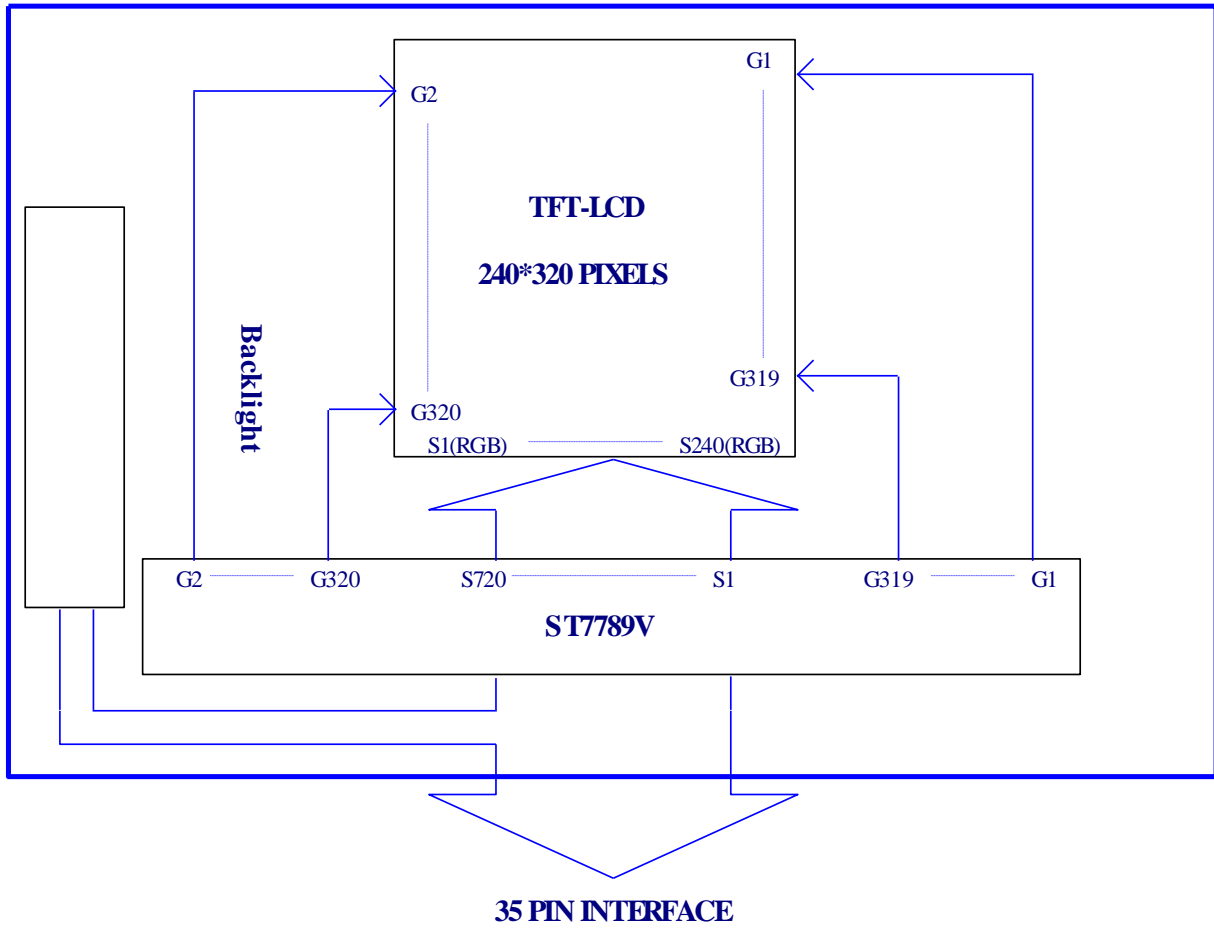


8. Interface Pin Assignment:

No.	Symbol	Function																																																																																												
1	GND	Ground																																																																																												
2	IM0	Select MPU Interface mode <table border="1" style="margin-left: 20px;"> <thead> <tr> <th>IM1</th> <th>IM0</th> <th>MCU-Interface Mode</th> <th>DB Pin in use</th> </tr> </thead> <tbody> <tr> <td>0</td> <td>0</td> <td>80 MCU 16-bit bus interface II</td> <td>D[17:10],D[8:1]</td> </tr> <tr> <td>0</td> <td>1</td> <td>80 MCU 8-bit bus interface II</td> <td>D[17:10]</td> </tr> <tr> <td>1</td> <td>0</td> <td>80 MCU 18-bit bus interface II</td> <td>D[17:0]</td> </tr> <tr> <td>3</td> <td>IM1</td> <td> <table border="1" style="margin-left: 20px;"> <tbody> <tr> <td>1</td> <td>1</td> <td>80 MCU 9-bit bus interface II</td> <td>D[17:9]</td> </tr> </tbody> </table> </td> </tr> <tr> <td>4</td> <td>TE</td> <td>Tearing effect signal is used to MCU to frame memory writing</td> </tr> <tr> <td>5</td> <td>GND</td> <td>Ground</td> </tr> <tr> <td>6</td> <td>DB17</td> <td>Data bus</td> </tr> <tr> <td>7</td> <td>DB16</td> <td>Data bus</td> </tr> <tr> <td>8</td> <td>DB15</td> <td>Data bus</td> </tr> <tr> <td>9</td> <td>DB14</td> <td>Data bus</td> </tr> <tr> <td>10</td> <td>DB13</td> <td>Data bus</td> </tr> <tr> <td>11</td> <td>DB12</td> <td>Data bus</td> </tr> <tr> <td>12</td> <td>DB11</td> <td>Data bus</td> </tr> <tr> <td>13</td> <td>DB10</td> <td>Data bus</td> </tr> <tr> <td>14</td> <td>DB9</td> <td>Data bus</td> </tr> <tr> <td>15</td> <td>DB8</td> <td>Data bus</td> </tr> <tr> <td>16</td> <td>IOVCC</td> <td>Digital power supply</td> </tr> <tr> <td>17</td> <td>DB7</td> <td>Data bus</td> </tr> <tr> <td>18</td> <td>DB6</td> <td>Data bus</td> </tr> <tr> <td>19</td> <td>DB5</td> <td>Data bus</td> </tr> <tr> <td>20</td> <td>DB4</td> <td>Data bus</td> </tr> <tr> <td>21</td> <td>DB3</td> <td>Data bus</td> </tr> <tr> <td>22</td> <td>DB2</td> <td>Data bus</td> </tr> <tr> <td>23</td> <td>DB1</td> <td>Data bus</td> </tr> <tr> <td>24</td> <td>DB0</td> <td>Data bus</td> </tr> <tr> <td>25</td> <td>/CS</td> <td>Chip select signal active low</td> </tr> <tr> <td>26</td> <td>RS</td> <td>Display data/command selection pin in parallel interface.</td> </tr> </tbody> </table>	IM1	IM0	MCU-Interface Mode	DB Pin in use	0	0	80 MCU 16-bit bus interface II	D[17:10],D[8:1]	0	1	80 MCU 8-bit bus interface II	D[17:10]	1	0	80 MCU 18-bit bus interface II	D[17:0]	3	IM1	<table border="1" style="margin-left: 20px;"> <tbody> <tr> <td>1</td> <td>1</td> <td>80 MCU 9-bit bus interface II</td> <td>D[17:9]</td> </tr> </tbody> </table>	1	1	80 MCU 9-bit bus interface II	D[17:9]	4	TE	Tearing effect signal is used to MCU to frame memory writing	5	GND	Ground	6	DB17	Data bus	7	DB16	Data bus	8	DB15	Data bus	9	DB14	Data bus	10	DB13	Data bus	11	DB12	Data bus	12	DB11	Data bus	13	DB10	Data bus	14	DB9	Data bus	15	DB8	Data bus	16	IOVCC	Digital power supply	17	DB7	Data bus	18	DB6	Data bus	19	DB5	Data bus	20	DB4	Data bus	21	DB3	Data bus	22	DB2	Data bus	23	DB1	Data bus	24	DB0	Data bus	25	/CS	Chip select signal active low	26	RS	Display data/command selection pin in parallel interface.
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26	RS	Display data/command selection pin in parallel interface.																																																																																												

		Display data(RS=1) / Command selection(RS=0)
27	WR	Write enable in MCU parallel interface
28	RD	Read enable in MCU parallel interface
29	/RESET	Reset signal active low
30	VCI	Analog power supply
31	GND	Ground
32	LED+	LED power supply(+)
33	GND	Ground
34	LED-	LED power supply(-)
35	GND	Ground

9. Block Diagram:



10. Backlight:

1. Standard Lamp Styles (Edge Lighting Type):
The LED chips are distributed over the edge light area of the illumination unit, which gives the less power consumption:
2. The Main Advantages of the LED Backlight are as following:
 - 2.1 The brightness of the backlight can simply be adjusted.
By a resistor or a potentiometer.

3. Data About LED Backlight:

(Ta=25°C)

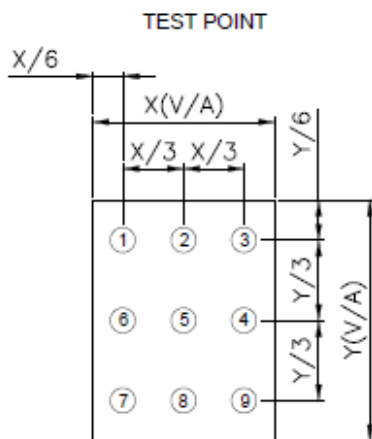
PARAMETER	Sym.	Min.	Typ.	Max.	Unit	Test Condition	Note
Supply Current	I	-	40	-	mA		
Supply Voltage	V	8.5	9.6	10.2	V		
Luminous Intensity for LCM	IV	500	600	-	Cd/m ²	If=40mA	2
Uniformity for LCM	-	70	-	-	%		3
Life Time	-	20000	-	-	Hr.		4
Color	White						

NOTE:

1. Backlight Only
2. Average Luminous Intensity of P1-P9
3. Uniformity = Min/Max * 100%
4. LED life time defined as follows: The final brightness is at 50% of original brightness

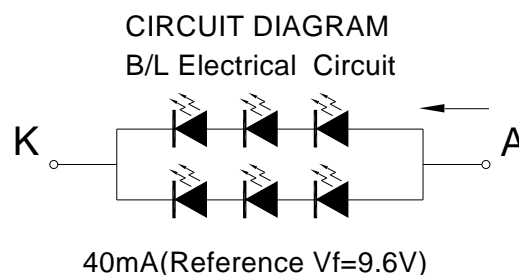
Measured Method: (X*Y: Light Area)

Internal Circuit Diagram



(Effective spatial Distribution)

Using aperture of 1° , distance 50cm.



11. Standard Specification for Reliability :

11-1. Standard Specifications for Reliability of LCD Module

No	Item	Description
01	High temperature operation	The sample should be allowed to stand at 70°C for 120 hours under driving condition and then returning it to normal temperature condition, and allowing it stand for 2 hours.
02	Low temperature operation	The sample should be allowed to stand at -20°C for 120 hours under driving condition and then returning it to normal temperature condition, and allowing it stand for 2 hours.
03	High temperature storage	The sample should be allowed to stand at 80°C for 240 hours under no-load condition, and then returning it to normal temperature condition, and allowing it stand for 2 hours.
04	Low temperature storage	The sample should be allowed to stand at -30°C for 240 hours under no-load condition, then returning it to normal temperature condition, and allowing it stand for 2 hours.
05	Moisture storage	The sample should be allowed to stand at 60°C,90%RH MAX for 240 hours under no-load condition, then taking it out and drying it at normal temperature for 2 hours.
06	Thermal shock storage	The sample should be allowed to stand the following 10 cycles : -30°C for 30 minutes → normal temperature for 5 minutes → +80°C for 30 minutes → normal temperature for 5 minutes, as one cycle.
07	Packing vibration	Frequency range : 10Hz ~ 55Hz Amplitude of vibration : 1.5mm Sweep time: 12 min X,Y,Z 2 hours for each direction.
08	Packing drop test	According to ISTA 1A 2001.
09	Electrical Static Discharge	Air: ±4KV 150pF/330Ω 5 times
		Contact: ±2KV 150pF/330Ω 5 time

*Sample size for each test item is 3~5pcs

11 - 2. Testing Conditions and Inspection Criteria

For the final test the testing sample must be stored at room temperature for 24 hours, after the tests listed in Table 12.1, Standard specifications for Reliability have been executed in order to ensure stability.

No	Item	Test Model	In section Criteria
01	Current Consumption	Refer To Specification	The current consumption should conform to the product specification.
02	Contrast	Refer To Specification	After the tests have been executed, the contrast must be larger than half of its initial value prior to the tests.
03	Appearance	Visual inspection	Defect free.

11- 3. MTBF

MTBF	Functions, performance, appearance, etc. shall be free from remarkable deterioration within 50,000 hours under ordinary operating and storage conditions room temperature (25±5°C), normal humidity (50±10% RH), and in area not exposed to direct sun light.
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12. Specification of Quality Assurance:

12-1. Purpose

This standard for Quality Assurance should affirm the quality of LCD module products to supply to purchaser by YEEBO CORPORATION (Supplier).

12-2. Standard for Quality Test

a. Inspection:

Before delivering, the supplier should take the following tests, and affirm the quality of product.

b. Electro-Optical Characteristics:

According to the individual specification to test the product.

c. Test of Appearance Characteristics:

According to the individual specification to test the product.

d. Test of Reliability Characteristics:

According to the definition of reliability on the specification for testing products.

e. Delivery Test:

Before delivering, the supplier should take the delivery test.

(i) Test method: According to **ISO2859-1**. General Inspection Level II take a single time.

(ii) The defects classify of AQL as following:

Major defect: AQL = 0.65

Minor defect: AQL = 2.5

Total defects: AQL = 2.5

12-3. Non- conforming Analysis & Deal With Manners

a. Non- conforming Analysis:

(i) Purchaser should supply the detail data of non- conforming sample and the non-conforming.

(ii) After accepting the detail data from purchaser, the analysis of non- conforming should be finished in two weeks.

(iii) If supplier can not finish analysis on time, must announce purchaser before 3 days.

b. Disposition of non- conforming:

(i) If find any product defect of supplier during assembly time, supplier must change the good product for every defect after recognition.

(ii) Both supplier and customer should analyze the reason and discuss the disposition of non- conforming when the reason of nonconforming is not sure.

12-4. Agreement items

Both sides should discuss together when the following problems happen.

a. There is any problem of standard of quality assurance, and both sides should think that must be modified.

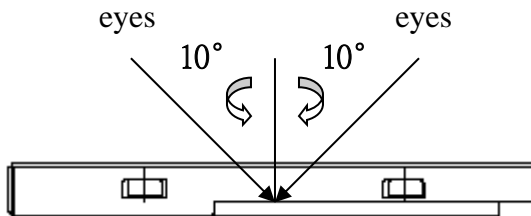
b. There is any argument item which does not record in the standard of quality assurance.

c. Any other special problem.

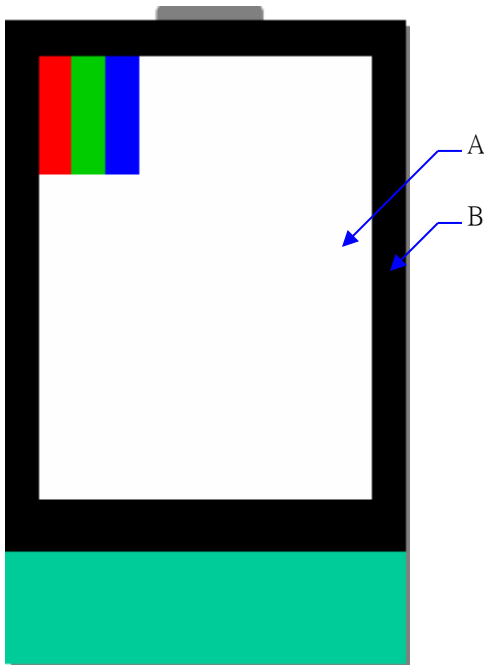
12-5. Standard of The Product Appearance Test

a. Manner of appearance test:

- (i) The test must be under 20W × 2 or 40W fluorescent light, and the distance of view must be at 30±5cm.
- (ii) When test the model of transmissive product must add the reflective plate.
- (iii) The test direction is base on around 10° of vertical line.
- (iiii) Temperature: 25±5°C Humidity: 60±10%RH



(iv) Definition of area:



A. Area: Viewing area.

B. Area: Out of viewing area.

(Outside viewing area)

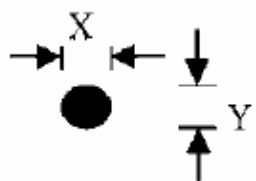
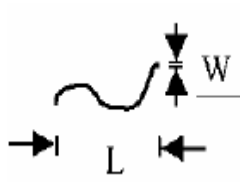
b. Basic principle:

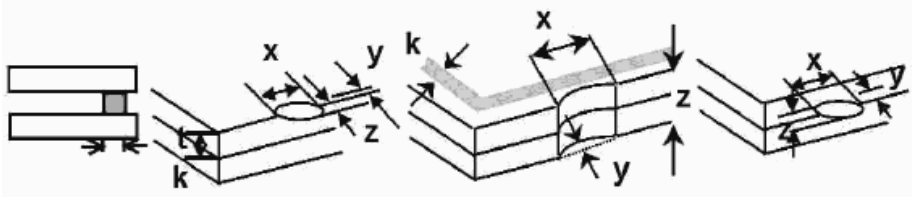
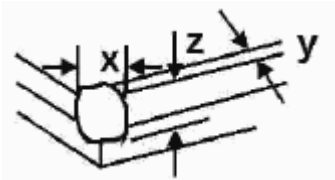
- (i) It will accord to the AQL when the standard can not be described.
- (ii) The sample of the lowest acceptable quality level must be discussed by both supplier and customer when any dispute happened.
- (iii) Must add new item on time when it is necessary.

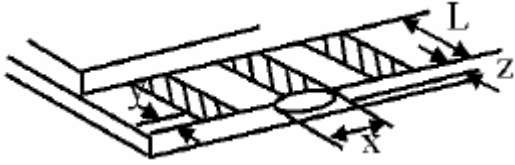
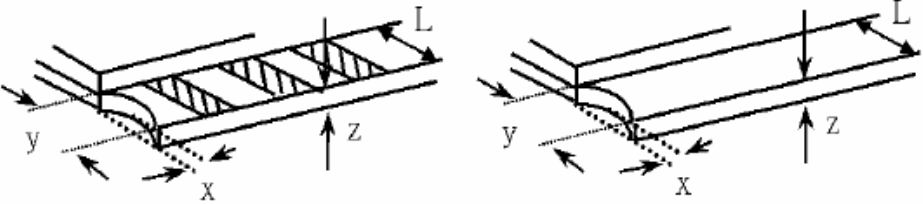
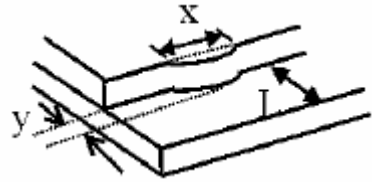
c. Standard of inspection: (Unit: mm)

12-6. Inspection specification

Defect out of viewing area can be neglected.

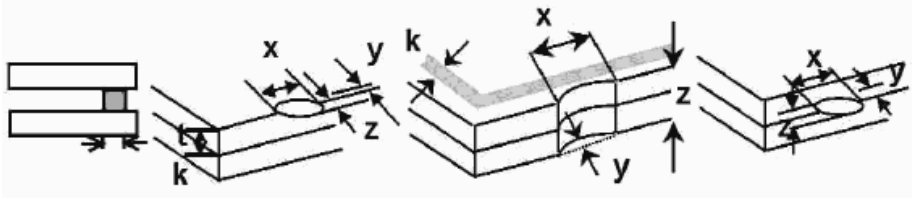
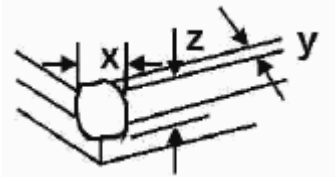
NO	Item	Criterion	AQL												
01	Electrical Testing	1.1 Missing vertical, horizontal segment, segment contrast defect. 1.2 Missing character, dot or icon. 1.3 Display malfunction. 1.4 No function or no display. 1.5 Current consumption exceeds product specifications. 1.6 LCD viewing angle defect. 1.7 Mixed product types. 1.8 Flicker	0.65												
02	Black or White spots or Bright spots or Color spots on LCD (Display only)	2.1 White and black or color spots on display $\leq 0.25\text{mm}$, no more than Five spots. 2.2 Densely spaced: No more than three spots within 3mm. 2.3 Not visible through 5% ND filter	2.5												
03	LCD and Touch Panel black spots, white spots, contamination (non – display)	3.1 Round type: As following drawing $\Phi = (X+Y) / 2$  <table border="1" data-bbox="810 990 1343 1240"> <thead> <tr> <th>Size(mm)</th> <th>Acceptable Q'ty</th> </tr> </thead> <tbody> <tr> <td>$\Phi \leq 0.10$</td> <td>Accept no dense</td> </tr> <tr> <td>$0.10 < \Phi \leq 0.20$</td> <td>2</td> </tr> <tr> <td>$0.20 < \Phi \leq 0.25$</td> <td>2</td> </tr> <tr> <td>$0.25 < \Phi \leq 0.30$</td> <td>1</td> </tr> <tr> <td>$0.30 < \Phi$</td> <td>0</td> </tr> </tbody> </table> <p>* Densely spaced: No more than two spots within 3mm.</p>	Size(mm)	Acceptable Q'ty	$\Phi \leq 0.10$	Accept no dense	$0.10 < \Phi \leq 0.20$	2	$0.20 < \Phi \leq 0.25$	2	$0.25 < \Phi \leq 0.30$	1	$0.30 < \Phi$	0	2.5
		Size(mm)	Acceptable Q'ty												
$\Phi \leq 0.10$	Accept no dense														
$0.10 < \Phi \leq 0.20$	2														
$0.20 < \Phi \leq 0.25$	2														
$0.25 < \Phi \leq 0.30$	1														
$0.30 < \Phi$	0														
3.2 Line type: (As following drawing)  <table border="1" data-bbox="715 1393 1343 1671"> <thead> <tr> <th>Length(mm)</th> <th>Width(mm)</th> <th>Acceptable Q'ty</th> </tr> </thead> <tbody> <tr> <td>---</td> <td>$W \leq 0.02$</td> <td>Accept no dense</td> </tr> <tr> <td>$L \leq 3.0$</td> <td>$0.02 < W \leq 0.05$</td> <td rowspan="2">2</td> </tr> <tr> <td>$L \leq 2.5$</td> <td>$0.03 < W \leq 0.08$</td> </tr> <tr> <td>---</td> <td>$0.08 < W$</td> <td>Rejection</td> </tr> </tbody> </table> <p>* Densely spaced: No more than two lines within 3mm.</p>	Length(mm)	Width(mm)	Acceptable Q'ty	---	$W \leq 0.02$	Accept no dense	$L \leq 3.0$	$0.02 < W \leq 0.05$	2	$L \leq 2.5$	$0.03 < W \leq 0.08$	---	$0.08 < W$	Rejection	2.5
Length(mm)	Width(mm)	Acceptable Q'ty													
---	$W \leq 0.02$	Accept no dense													
$L \leq 3.0$	$0.02 < W \leq 0.05$	2													
$L \leq 2.5$	$0.03 < W \leq 0.08$														
---	$0.08 < W$	Rejection													

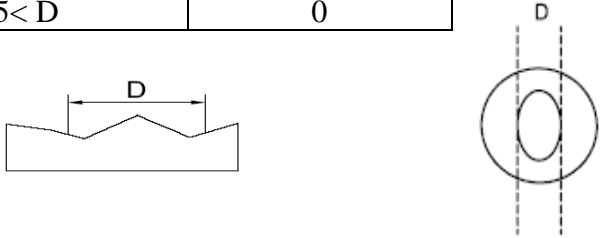
NO	Item	Criterion	AQL																		
04	Polarizer bubbles	<p>If bubbles are visible, judge using black spot specifications, not easy to find, must check in specify direction</p> <table border="1"> <thead> <tr> <th>Size Φ(mm)</th> <th>Acceptable Q'ty</th> </tr> </thead> <tbody> <tr> <td>$\Phi \leq 0.20$</td> <td>Accept no dense</td> </tr> <tr> <td>$0.20 < \Phi \leq 0.50$</td> <td>3</td> </tr> <tr> <td>$0.50 < \Phi \leq 1.00$</td> <td>2</td> </tr> <tr> <td>$1.00 < \Phi$</td> <td>0</td> </tr> <tr> <td>Total Q'ty</td> <td>3</td> </tr> </tbody> </table>	Size Φ (mm)	Acceptable Q'ty	$\Phi \leq 0.20$	Accept no dense	$0.20 < \Phi \leq 0.50$	3	$0.50 < \Phi \leq 1.00$	2	$1.00 < \Phi$	0	Total Q'ty	3	2.5						
Size Φ (mm)	Acceptable Q'ty																				
$\Phi \leq 0.20$	Accept no dense																				
$0.20 < \Phi \leq 0.50$	3																				
$0.50 < \Phi \leq 1.00$	2																				
$1.00 < \Phi$	0																				
Total Q'ty	3																				
05	Scratches	Follow NO.3 -2 Line Type.																			
06	Mura	Not visible through 5% ND filter in 50% gray.	2.5																		
07	Chipped glass	<p>Symbols: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: LCD side length L: Electrode pad length</p> <p>7.1 General glass chip: 7.1.1 Chip on panel surface and crack between panels:</p>  <table border="1"> <thead> <tr> <th>z: Chip thickness</th> <th>y: Chip width</th> <th>x: Chip length</th> </tr> </thead> <tbody> <tr> <td>$Z \leq 1/2t$</td> <td>Not over viewing area</td> <td>$x \leq 1/8a$</td> </tr> <tr> <td>$1/2t < z \leq 2t$</td> <td>Not exceed 1/3k</td> <td>$x \leq 1/8a$</td> </tr> </tbody> </table> <p>⊙ Unit: mm ⊙ If there are 2 or more chips, x is the total length of each chip</p> <p>7.1.2 Corner crack:</p>  <table border="1"> <thead> <tr> <th>z: Chip thickness</th> <th>y: Chip width</th> <th>x: Chip length</th> </tr> </thead> <tbody> <tr> <td>$Z \leq 1/2t$</td> <td>Not over viewing area</td> <td>$x \leq 1/8a$</td> </tr> <tr> <td>$1/2t < z \leq 2t$</td> <td>Not exceed 1/3k</td> <td>$x \leq 1/8a$</td> </tr> </tbody> </table> <p>⊙ Unit: mm ⊙ If there are 2 or more chips, x is the total length of each chip</p>	z: Chip thickness	y: Chip width	x: Chip length	$Z \leq 1/2t$	Not over viewing area	$x \leq 1/8a$	$1/2t < z \leq 2t$	Not exceed 1/3k	$x \leq 1/8a$	z: Chip thickness	y: Chip width	x: Chip length	$Z \leq 1/2t$	Not over viewing area	$x \leq 1/8a$	$1/2t < z \leq 2t$	Not exceed 1/3k	$x \leq 1/8a$	2.5
z: Chip thickness	y: Chip width	x: Chip length																			
$Z \leq 1/2t$	Not over viewing area	$x \leq 1/8a$																			
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NO	Item	Criterion	AQL																
08	Glass crack	<p>Symbols: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: LCD side length L: Electrode pad length</p> <p>8.1 Protrusion over terminal: 8.1.1 Chip on electrode pad:</p>  <table border="1" data-bbox="539 645 1225 801"> <tr> <td>y: Chip width</td> <td>x: Chip length</td> <td>z: Chip thickness</td> </tr> <tr> <td>$y \leq 0.5\text{mm}$</td> <td>$x \leq 1/8a$</td> <td>$0 < z \leq t$</td> </tr> </table> <p>8.1.2 Non-conductive portion:</p>  <table border="1" data-bbox="539 1160 1225 1317"> <tr> <td>y: Chip width</td> <td>x: Chip length</td> <td>z: Chip thickness</td> </tr> <tr> <td>$y \leq L$</td> <td>$x \leq 1/8a$</td> <td>$0 < z \leq t$</td> </tr> </table> <p>⊙ If there chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications. ⊙ If the product will be heat sealed by the customer, the alignment mark must not be damaged.</p> <p>8.1.3 Substrate protuberance and internal crack</p>  <table border="1" data-bbox="858 1630 1300 1787"> <tr> <td>y: width</td> <td>x: length</td> </tr> <tr> <td>$y \leq 1/3L$</td> <td>$X \leq a$</td> </tr> </table>	y: Chip width	x: Chip length	z: Chip thickness	$y \leq 0.5\text{mm}$	$x \leq 1/8a$	$0 < z \leq t$	y: Chip width	x: Chip length	z: Chip thickness	$y \leq L$	$x \leq 1/8a$	$0 < z \leq t$	y: width	x: length	$y \leq 1/3L$	$X \leq a$	2.5
y: Chip width	x: Chip length	z: Chip thickness																	
$y \leq 0.5\text{mm}$	$x \leq 1/8a$	$0 < z \leq t$																	
y: Chip width	x: Chip length	z: Chip thickness																	
$y \leq L$	$x \leq 1/8a$	$0 < z \leq t$																	
y: width	x: length																		
$y \leq 1/3L$	$X \leq a$																		

NO	Item	Criterion	AQL
09	Cracked glass	The LCD with extensive crack is not acceptable.	2.5
10	Backlight elements	10.1 Illumination source flickers when lit. 10.2 Spots or scratches that appear when lit must be judged. Using LCD spot, lines and contamination standards. 10.3 Backlight doesn't light or color is wrong.	2.5 2.5 0.65
11	Bezel	Bezel must comply with product specifications.	2.5
12	PCB、COB	12.1 COB seal may not have pinholes larger than 0.2mm or contamination. 12.2 COB seal surface may not have pinholes through to the IC. 12.3 The height of the COB should not exceed the height indicated in the assembly diagram. 12.4 There may not be more than 2mm of sealant outside the seal area on PCB. And there should be no more than three places. 12.5 Parts on PCB must be the same as on the production characteristic chart, There should be no wrong parts, missing parts or excess parts. 12.6 The jumper on the PCB should conform to the product characteristic chart. 12.7 PCBA cosmetic control base on latest IPC standard,IPC-A-610,acceptalbe limit of grade 2.	2.5 2.5 2.5 2.5 0.65 0.65 2.5
13	FPC	13.1 FPC terminal damage \leq 1/2 FPC terminal width and can not affect the function , we judge accept. 13.2 FPC alignment hole damage \leq 1/2 alignment area and can not affect the function , we judge accept.	2.5 2.5
14	Soldering	14.1 No cold solder joints, missing solder connections, oxidation or icicle. 14.2 No short circuits in components on PCB or FPC.	2.5 0.65

NO	Item	Criterion	AQL
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15	Touch Panel Chipped glass	<p>Symbols: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Touch Panel Total thickness a: LCD side length L: Electrode pad length</p> <p>15.1 General glass chip: 15.1.1 Chip on panel surface and crack between panels:</p>  <table border="1" data-bbox="395 725 1217 943"> <tr> <td>z: Chip thickness</td> <td>y: Chip width</td> <td>x: Chip length</td> </tr> <tr> <td>$Z \leq t$</td> <td>$\leq 1/2 k$ and not over viewing area</td> <td>$x \leq 1/8a$</td> </tr> </table> <p>⊙ Unit: mm ⊙ If there are 2 or more chips, x is the total length of each chip</p> <p>15.1.2 Corner crack:</p>  <table border="1" data-bbox="395 1323 1217 1541"> <tr> <td>z: Chip thickness</td> <td>y: Chip width</td> <td>x: Chip length</td> </tr> <tr> <td>$z \leq t$</td> <td>$\leq 1/2 k$ and not over viewing area</td> <td>$x \leq 1/8a$</td> </tr> </table> <p>⊙ Unit: mm ⊙ If there are 2 or more chips, x is the total length of each chip</p>	z: Chip thickness	y: Chip width	x: Chip length	$Z \leq t$	$\leq 1/2 k$ and not over viewing area	$x \leq 1/8a$	z: Chip thickness	y: Chip width	x: Chip length	$z \leq t$	$\leq 1/2 k$ and not over viewing area	$x \leq 1/8a$	2.5
z: Chip thickness	y: Chip width	x: Chip length													
$Z \leq t$	$\leq 1/2 k$ and not over viewing area	$x \leq 1/8a$													
z: Chip thickness	y: Chip width	x: Chip length													
$z \leq t$	$\leq 1/2 k$ and not over viewing area	$x \leq 1/8a$													

NO	Item	Criterion	AQL										
16	Touch Panel(Fish eye、dent and bubble on film)	<table border="1"> <thead> <tr> <th>SIZE(mm)</th> <th>Acceptable Q'ty</th> </tr> </thead> <tbody> <tr> <td>$\Phi \leq 0.2$</td> <td>Accept no dense</td> </tr> <tr> <td>$0.2 < D \leq 0.4$</td> <td>5</td> </tr> <tr> <td>$0.4 < D \leq 0.5$</td> <td>2</td> </tr> <tr> <td>$0.5 < D$</td> <td>0</td> </tr> </tbody> </table> 	SIZE(mm)	Acceptable Q'ty	$\Phi \leq 0.2$	Accept no dense	$0.2 < D \leq 0.4$	5	$0.4 < D \leq 0.5$	2	$0.5 < D$	0	2.5
SIZE(mm)	Acceptable Q'ty												
$\Phi \leq 0.2$	Accept no dense												
$0.2 < D \leq 0.4$	5												
$0.4 < D \leq 0.5$	2												
$0.5 < D$	0												
17	Touch Panel Newton ring	Newton ring dimension $\leq 1/2$ touch panel area and not affect font and line distortion($\leq 2.5\%$) , it is acceptable.	2.5										
18	Touch Panel Linearity	Less than 2.5% is acceptable.	2.5										
19	LCD Ripple	Touch the touch panel , can not see the LCD ripple. Pen: R 1.0mm silicon rubber. Operation Force: 80g	2.5										
20	General appearance	20.1 Pin type must match type in specification sheet. 20.2 LCD pin loose or missing pins. 20.3 Product packaging must the same as specified on packaging specification sheet. 20.4 Product dimension and structure must conform to product specification sheet.	0.65 0.65 0.65 0.65										

13. Handling Precaution:

13-1 Handling of LCM

- Don't give external shock.
- Don't apply excessive force on the surface.
- Liquid in LCD is hazardous substance. Must not lick and swallow. when the liquid is attach to your hand, skin, cloth etc. Wash it out thoroughly and immediately.
- Don't operate it above the absolute maximum rating.
- Don't disassemble the LCM.
- The operators should be grounded whenever he/she comes into contact with the module. Never touch any of the conductive parts such as the LSI pads, the copper leads on the PCB and the interface terminals with any parts of the human body.
- The modules should be kept in antistatic bags or other containers resistant to static for storage.
- The module is coated with a film to protect the display surface. Be care when peeling off this protective film since static electricity may be generated.

13-2 Storage

- Store in an ambient temperature of $25\pm 10^{\circ}\text{C}$, and in a relative humidity of $50\pm 10\% \text{RH}$. Don't expose to sunlight or fluorescent light.
- Storage in a clean environment, free from dust, active gas, and solvent.
- Store in anti-static electricity container.
- Store without any physical load.

13-3 Soldering

- Use only soldering irons with proper grounding and no leakage.
- Iron: No higher than $310\pm 10^{\circ}\text{C}$ and less than 3 sec during Hand soldering.
- Rewiring: no more than 2 times.

14. Warranty

This product has been manufactured to specifications as a part for use in your company's general electronic products. It is guaranteed to perform according to delivery specifications. For any other

use apart from general electronic equipment, we will not take responsibility if the product is used in

medical devices, nuclear power control equipment, aerospace equipment, fire and security systems,

or any other applications in which there is a direct risk to human life and where extremely high levels of reliability are required. If the product is to be used in any of the above applications, we will need to enter into a separate product liability agreement.

1. We cannot accept responsibility for any defect arise after additional process of the product (including disassembly and reassembly), after product delivery.

2. We cannot accept responsibility for any defect, which may arise after the application of strong external force to the product.

3. We cannot accept responsibility for any defect, which may arise due to the application of static

electricity after the product has passed your company's acceptance inspection procedures.

4. We can not accept responsibility for industrial property, which may arise through the use of your product , with exception to those issues relating directly to the structure or method of manufacturing of our product within one year from YEEBO shipment.

5. For Heatseal Product which required to heatseal by customer side, parts must be used within three months after delivery from factory.

6. For TAB Product which required to solder by customer side, parts must be used within three months after delivery from factory.

7. The liability of YB is limited to repair or replacement on the terms set forth below. YB will not be responsible for any subsequent or consequential events or injury or damage to any personnel or

user including third party personnel and/or user. Unless otherwise agreed in writing between YB and the customer, YB will only replace or repair any of its LCD which is found defective electrically or visually when inspected in accordance with YB GENERAL LCD INSPECTION STANDARD.

15. Guarantee:

Our products meet requirements of the environment.

YEEBO ROHS requirement is based on European Union Directive 2011/65/EU

(ROHS)

Requirements and Update.